

**IN THE CLAIMS**

Please amend the claims as follows:

Claims 1-15 (canceled)

Claim 16 (currently amended): A process for producing a ceramic heater, comprising:  
forming a resistance heating element on a surface of a ceramic substrate;  
dividing the resistance heating element into plural sections;  
measuring ~~resistivities~~ a resistivity of each of said plural sections, ~~respectively~~; and  
trimming ~~each of said plural sections according to a comparison between the~~  
~~resistivities of said plural sections~~ the resistance heating element so as to adjust the resistivity  
of each of said plural sections to a desired value.

Claim 17 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein the trimming step includes trimming a side face of the resistance heating element.

Claim 18 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein the trimming step includes trimming a surface of the resistance heating element.

Claim 19 (currently amended): The process for producing a ceramic heater according to claim 16,

wherein the forming step comprises[[],]:

providing a conductor containing paste layer on the surface of the ceramic substrate[[],];

and

firing the ceramic substrate with the conductor containing paste layer.

Claim 20 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

Claim 21 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein said ceramic substrate has Ra of 10  $\mu\text{m}$  or less according to JIS B0601.

Claim 22 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein the resistance heating element has a thickness of 1 to 30  $\mu\text{m}$ .

Claim 23 (currently amended): The process for producing a ceramic heater according to claim 16,

wherein the resistance heating element ~~is divided into~~ comprises at least two circuits.

Claim 24 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein said ceramic substrate has a disc shape and has a diameter of 190 mm or more.

Claim 25 (previously presented): The process for producing a ceramic heater according to claim 16,

wherein said ceramic substrate has a thickness of 1.5 to 5 mm.

Claim 26 (new): The process for producing a ceramic heater according to claim 16, wherein the trimming includes applying a laser light to the resistance heating element.

Claim 27 (new): The process for producing a ceramic heater according to claim 16, wherein the trimming includes grinding a surface of the resistance heating element.

Claim 28 (new): The process for producing a ceramic heater according to claim 16, wherein the resistance heating element is configured to provide sufficient heat for at least one

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of producing and examining a semiconductor device.